

MECHANICAL CASE OUTLINE

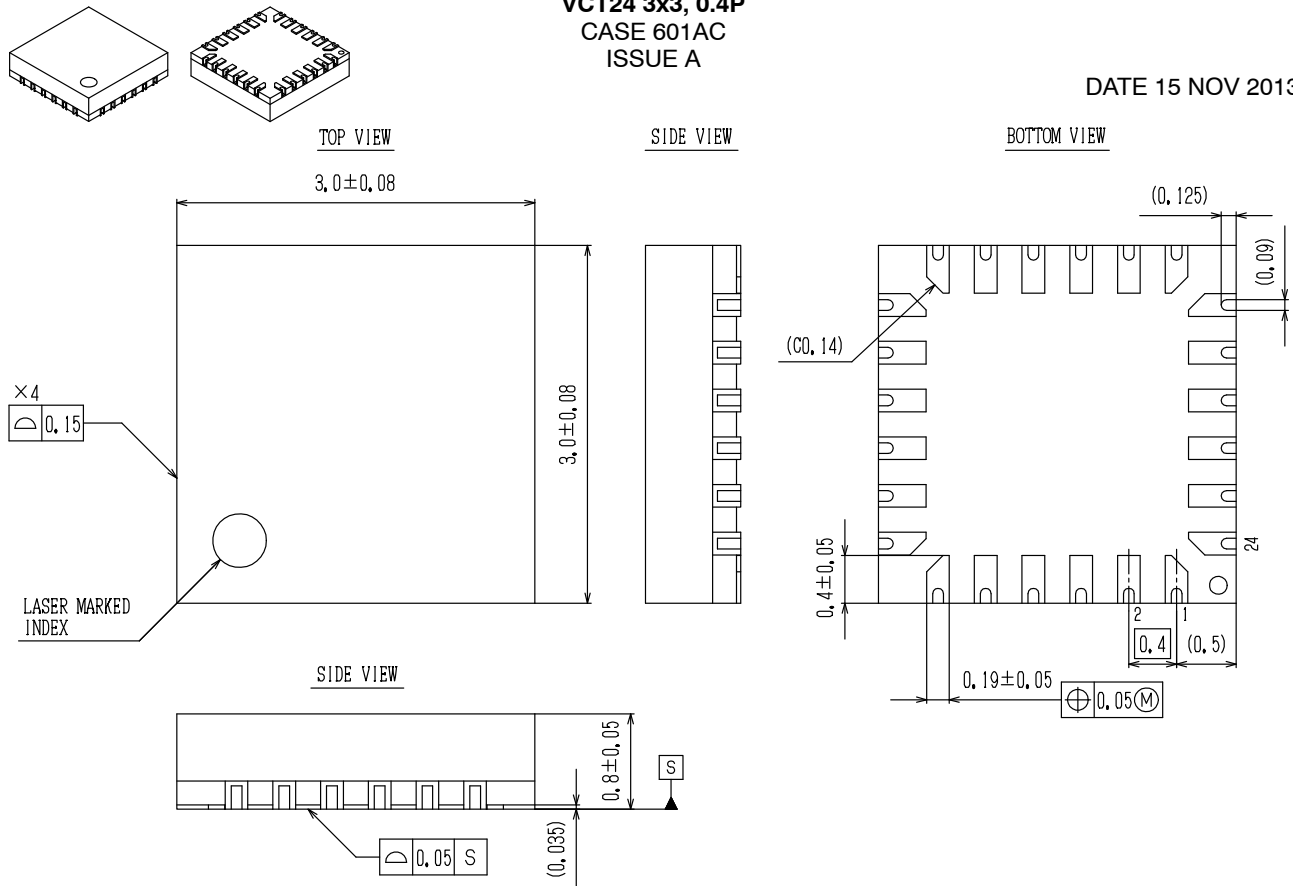
PACKAGE DIMENSIONS

ON Semiconductor®

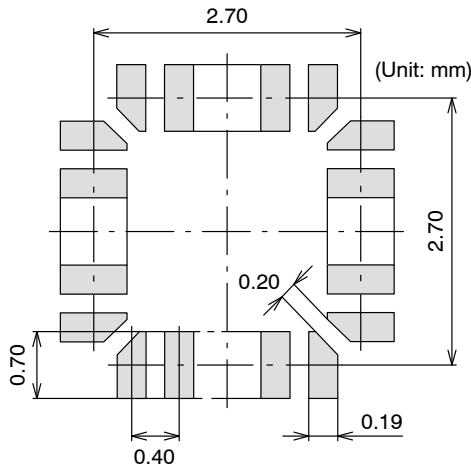


VCT24 3x3, 0.4P
CASE 601AC
ISSUE A

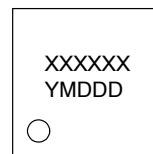
DATE 15 NOV 2013



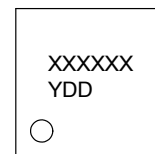
SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data



XXXXXX = Specific Device Code
Y = Year
DD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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